## IN THE SPECIFICATION

Please replace Table 2 on page 11 with the following amended Table 2:

| Mg doped p-type GaN contact layer  | 0.15μm   |
|--|----------|
| Mg doped p-type Al <sub>0.15</sub> Ga <sub>0.85</sub> N cladding layer                                     | 0.45µm   |
| Mg doped p-type GaN wave guiding layer   | 0.12μm   |
| Mg doped p-type Al <sub>0.2</sub> Ga <sub>0.8</sub> N electron blocking layer                              | 200      |
| In <sub>0.03</sub> Ga <sub>0.97</sub> N/In <sub>0.16</sub> Ga <sub>0.74</sub> N 3-period MQWs active layer |          |
| In <sub>0.10</sub> GaN <sub>0.90</sub> N well layer  | 35[[□]]  |
| In <sub>0.03</sub> Ga <sub>0.97</sub> N barrier layer  | 50[[□]]  |
| Si doped n-type GaN wave guiding layer   | 0.12μm   |
| Si doped n-type Al <sub>0.15</sub> Ga <sub>0.85</sub> N cladding layer                                     | 0.45μm   |
| Si doped n-type In <sub>0.1</sub> Ga <sub>0.9</sub> N  | 500[[□]] |
| Si doped n-type GaN contact layer  | 3µm      |
| Un-doped n-type GaN  | 1µm      |
| Un-doped n-type ELO GaN layer  | 6µm      |
| Un-doped GaN template layer/Si₃N₄ mask   | 2μm      |
| GaN buffer   | 300      |
| Sapphire substrate   | 450μm    |

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